



# PF-709AD HALOGEN-FREE WATER-SOLUBLE PASTE FLUX

**USA:** 315 Fairbank St. Addison, IL • +1-630-6288083 • FAX +1-630-6286543

**EUROPE:** Unit 9 Apex Ct. Bassendale Rd. Bromborough, Wirral CH62 3RE • +44-151-3340888 • FAX +44-151-3461408

**SINGAPORE:** 6 Tuas South St. 5 Singapore 637790 • +65-67957757 • FAX +1-65-67957767

**PHILIPPINES:** Phase 1 Qualitek Ave. Mariveles, Bataan Philippines C-2106 • +63-47-9354163 • FAX +63-47-5613717

**CHINA:** 3B/F, YiFa Print Bldg. 351 JiHua Rd., Buji Shenzhen, China 518112 • +86-755-28522814 • FAX +86-755-28522787

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**DESCRIPTION**

PF-709AD Halogen-Free, Water-Soluble formulation is a mixture of organic acids, thixotropic thickeners and surfactants, which aid removal of post soldering residues. The fluxing activity of the paste flux is comparable to halogen/halide containing paste fluxes. This flux has been designed for dipping or pin transfer applications to deliver an optimum amount of paste flux onto the substrate. The high tackiness property provides excellent attachment of solder spheres onto BGA or CSP components. Paste flux is virtually free of air entrapment, resulting in consistent paste flux deposition.

**FEATURES**

- Water-Soluble
- Stable transfer volume
- Superior wetting with maximum activity
- Minimal spattering & thermally stable
- Excellent tackiness & stable viscosity
- Halogen-Free
- Broad process window

**APPLICATION METHODS**

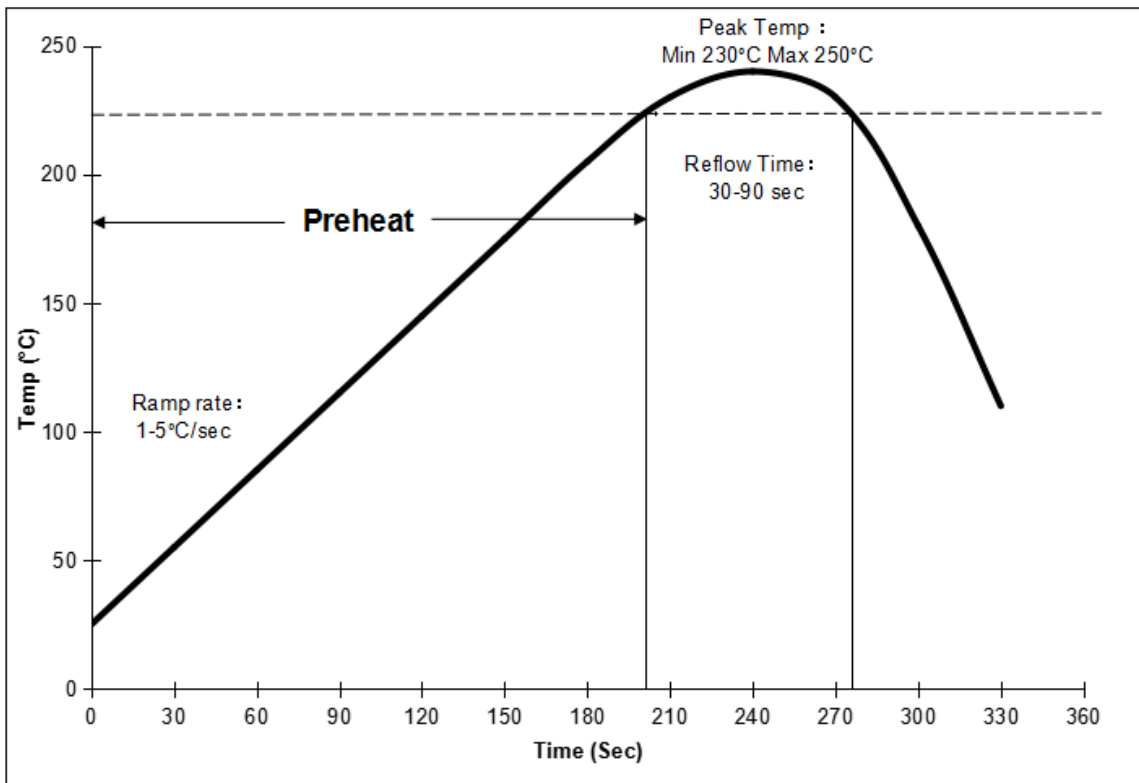
- Dipping
- Pin transfer

**PHYSICAL & CHEMICAL PROPERTIES**

PROPERTIES	SPECIFICATIONS	METHOD
Flux Classification	ORH0	IPC-J-STD-004B
Appearance	Amber	Visual
pH - 5% Aqueous Solution	2.5 – 4.5	QIT
Halide Content	Halide-Free	IPC-TM-650 2.3.33 (Silver Chromate Test)
Halogen Content	Halogen-Free	EN 14582
Malcom Viscosity (@10rpm)	10 - 30 Pa.s	IPC-TM-650 2.4.34.3 (Modified)
Tack Strength	100 - 200 gf	JIS Z 3284
Surface Insulation Resistance (Cleaned)	> 1.0 x 10 <sup>9</sup> ohms	IPC-TM-650 2.6.3.3

**REFLOW**

The following is a recommended profile for leadfree alloy:



Reflow can be accomplished in a nitrogen controlled atmosphere at  $\leq 100$  ppm oxygen levels. The initial ramp rate should be 1 – 5°C per second to a peak temperature of 230 – 250°C. The time over liquidus temperature should be 30 - 90 seconds. The profile is recommended to the user as reference, and should be optimized by the user to meet individual process needs.

**RESIDUE REMOVAL & CLEANING**

PF-709AD is water soluble formulation therefore the residues need to be removed. Residue removal can be achieved with the use of hot de-ionized water in either a batch or conveyORIZED cleaner. Water temperature should be 40 - 60°C with water pressure of 35 - 65 psi.

**PACKAGING**

PF-709AD paste flux is available in 150 gm 6 oz cartridge. Other packaging can be provided upon request.

**STORAGE & HANDLING**

PF-709AD may be stored at ambient temperature or refrigerated. Shelf life of paste flux is 6 month when stored at 2 to 25°C. If refrigerated, allow paste flux to reach ambient temperature prior to use.

**SAFETY DATA SHEET**

Contact Sales for SDS.